

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :  
Yuuichiro KAJIWARA et al. : **Attn: APPLICATION BRANCH**  
Serial No. NEW : **Docket No. 2001\_1763A**  
Filed November 28, 2001 :

A LATEX FOR DIP MOLDING AND A DIP  
MOLDED PRODUCT

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,  
Washington, DC 20231

Sir:

Prior to calculating the filing fee, please amend the above-identified application as follows:

IN THE CLAIMS

*Please amend the claims as follows:*

4. **(Amended)** The latex for dip molding according to claim 1, wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

8. **(Amended)** The latex for dip molding according to claim 1, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

9. **(Amended)** The latex for dip molding according to claim 1, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (T<sub>g</sub>) of -50 to 50°C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

10. **(Amended)** A dip molded product produced by dip molding from the latex for dip molding described in claim 1.

FOR OFFICIAL USE ONLY

**REMARKS**

The claims are amended to remove the multiple dependencies, so as to remove the improper multiple dependencies and to reduce the PTO filing fee.

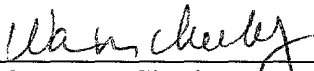
Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached pages are captioned "**Version with markings to show changes made**".

Favorable action on the merits is solicited.

Respectfully submitted,

Yuuichiro KAJIWARA et al.

By

  
\_\_\_\_\_  
Warren M. Cheek, Jr.  
Registration No. 33,367  
Attorney for Applicants

WMC/dlk  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
November 28, 2001

FOR FILING

Claims

Claim 1

A latex for dip molding, which is obtainable by emulsion polymerization of 100 parts by weight of a monomer mixture in the presence of 0.5 to 10.0 parts by weight of alkyl benzene sulfonate containing at least 10 weight % of C<sub>13-20</sub> alkyl benzene sulfonate.

Claim 2

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 25 weight % of C<sub>13-20</sub> alkyl benzene sulfonate.

Claim 3

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 40 weight % of C<sub>13-20</sub> alkyl benzene sulfonate.

Claim 4 (Amended)

The latex for dip molding according to ~~any one of claims 1 to 3,~~ wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

Claim 5

The latex for dip molding according to claim 4, wherein the redox type polymerization initiator containing no transition metal salt is a combination product of an oil-soluble peroxide with a reducing agent.

Claim 6

The latex for dip molding according to claim 5, wherein the reducing agent is an alkali metal sulfonate or ammonium sulfonate.

✓  
PAGE 36/66

Claim 7

The latex for dip molding according to claim 6, wherein the alkali metal sulfonate is sodium formaldehyde sulfoxylate.

Claim 8 (Amended)

The latex for dip molding according to ~~any one of claims 1 to 7~~, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

Claim 9 (Amended)

The latex for dip molding according to ~~any one of claims 1 to 8~~, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (Tg) of -50 to 50 °C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

Claim 10 (Amended)

A dip molded product produced by dip molding from the latex for dip molding described in ~~any one of claims 1 to 9~~.

Claim 11

The dip molded product according to claim 10, which is a glove or a fingerstalls.